



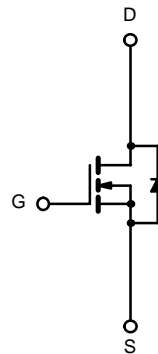
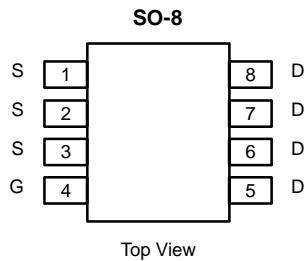
New Product

Si4442DY  
Vishay Siliconix

## N-Channel 30-V (D-S) MOSFET

**TrenchFET<sup>®</sup>**  
Power MOSFETs  
2.5-V Rated  
100% R<sub>G</sub> Tested

PRODUCT SUMMARY		
V <sub>DS</sub> (V)	r <sub>DS(on)</sub> (Ω)	I <sub>D</sub> (A)
30	0.0045 @ V <sub>GS</sub> = 10 V	22
	0.005 @ V <sub>GS</sub> = 4.5 V	19
	0.0075 @ V <sub>GS</sub> = 2.5 V	17



N-Channel MOSFET

ABSOLUTE MAXIMUM RATINGS (T <sub>A</sub> = 25 °C UNLESS OTHERWISE NOTED)					
Parameter	Symbol	10 secs	Steady State	Unit	
Drain-Source Voltage	V <sub>DS</sub>	30		V	
Gate-Source Voltage	V <sub>GS</sub>	±12			
Continuous Drain Current (T <sub>J</sub> = 150 °C) <sup>a</sup>	I <sub>D</sub>	T <sub>A</sub> = 25 °C	22	15	A
		T <sub>A</sub> = 70 °C	17	11	
Pulsed Drain Current (10 μs Pulse Width)	I <sub>DM</sub>	60			
Continuous Source Current (Diode Conduction) <sup>a</sup>	I <sub>S</sub>	2.9	1.3		
Maximum Power Dissipation <sup>a</sup>	P <sub>D</sub>	T <sub>A</sub> = 25 °C	3.5	1.6	W
		T <sub>A</sub> = 70 °C	2.2	1	
Operating Junction and Storage Temperature Range	T <sub>J</sub> , T <sub>stg</sub>	-55 to 150		°C	

THERMAL RESISTANCE RATINGS					
Parameter	Symbol	Typical	Maximum	Unit	
Maximum Junction-to-Ambient <sup>a</sup>	R <sub>thJA</sub>	t ≤ 10 sec	29	35	°C/W
		Steady State	67	80	
Maximum Junction-to-Foot (Drain)	R <sub>thJF</sub>	13	16		

Notes

a. Surface Mounted on 1" x 1" FR4 Board.

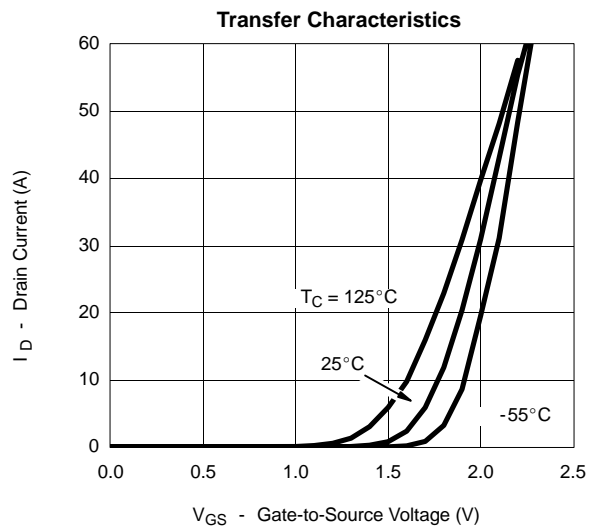
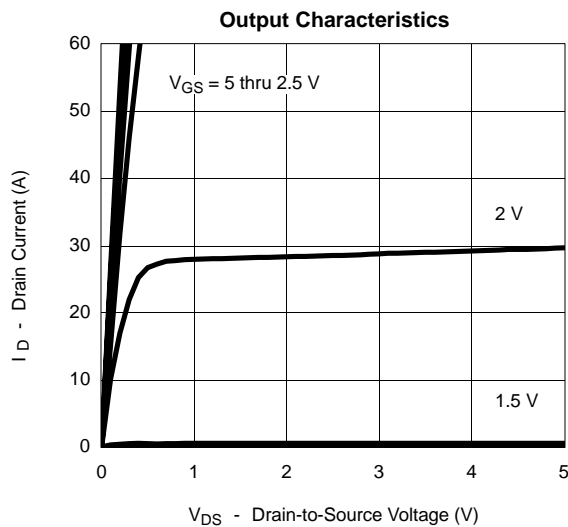


SPECIFICATIONS (T <sub>J</sub> = 25 °C UNLESS OTHERWISE NOTED)						
Parameter	Symbol	Test Condition	Min	Typ	Max	Unit
<b>Static</b>						
Gate Threshold Voltage	V <sub>GS(th)</sub>	V <sub>DS</sub> = V <sub>GS</sub> , I <sub>D</sub> = 250 μA	0.6			V
Gate-Body Leakage	I <sub>GSS</sub>	V <sub>DS</sub> = 0 V, V <sub>GS</sub> = ± 12 V			± 100	nA
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	V <sub>DS</sub> = 24 V, V <sub>GS</sub> = 0 V			1	μA
		V <sub>DS</sub> = 24 V, V <sub>GS</sub> = 0 V, T <sub>J</sub> = 55 °C			5	
On-State Drain Current <sup>a</sup>	I <sub>D(on)</sub>	V <sub>DS</sub> ≥ 5 V, V <sub>GS</sub> = 10 V	30			A
Drain-Source On-State Resistance <sup>a</sup>	r <sub>DS(on)</sub>	V <sub>GS</sub> = 10 V, I <sub>D</sub> = 22 A		0.0035	0.0045	Ω
		V <sub>GS</sub> = 4.5 V, I <sub>D</sub> = 19 A		0.0041	0.005	
		V <sub>GS</sub> = 2.5 V, I <sub>D</sub> = 17 A		0.0062	0.0075	
Forward Transconductance <sup>a</sup>	g <sub>fs</sub>	V <sub>DS</sub> = 15 V, I <sub>D</sub> = 22 A		100		S
Diode Forward Voltage <sup>a</sup>	V <sub>SD</sub>	I <sub>S</sub> = 2.9 A, V <sub>GS</sub> = 0 V		0.75	1.1	V
<b>Dynamic<sup>b</sup></b>						
Total Gate Charge	Q <sub>g</sub>	V <sub>DS</sub> = 15 V, V <sub>GS</sub> = 4.5 V, I <sub>D</sub> = 22 A		36	50	nC
Gate-Source Charge	Q <sub>gs</sub>			8		
Gate-Drain Charge	Q <sub>gd</sub>			10.5		
Gate Resistance	R <sub>G</sub>		0.5	1.5	2.6	Ω
Turn-On Delay Time	t <sub>d(on)</sub>	V <sub>DD</sub> = 15 V, R <sub>L</sub> = 15 Ω I <sub>D</sub> ≅ 1 A, V <sub>GEN</sub> = 10 V, R <sub>G</sub> = 6 Ω		17	30	ns
Rise Time	t <sub>r</sub>			11	20	
Turn-Off Delay Time	t <sub>d(off)</sub>			125	180	
Fall Time	t <sub>f</sub>			47	70	
Source-Drain Reverse Recovery Time	t <sub>rr</sub>		I <sub>F</sub> = 2.9 A, di/dt = 100 A/μs		50	

Notes

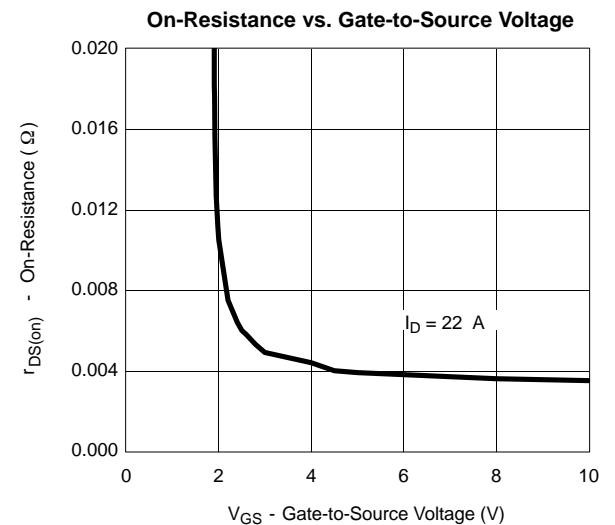
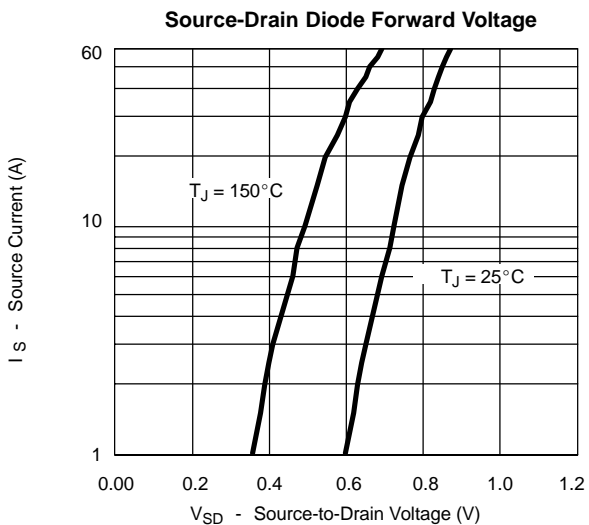
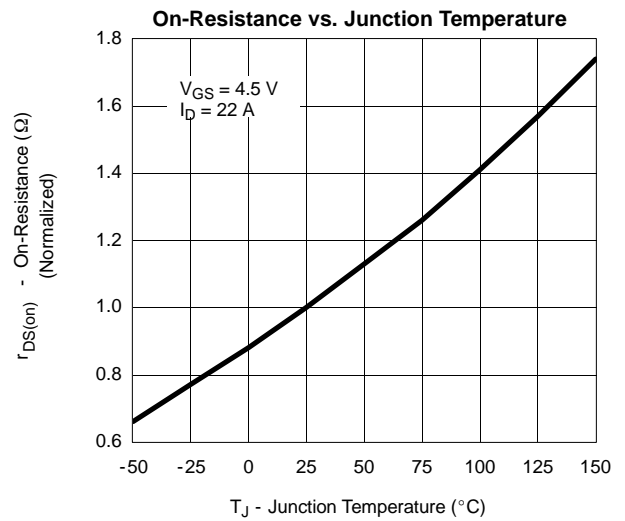
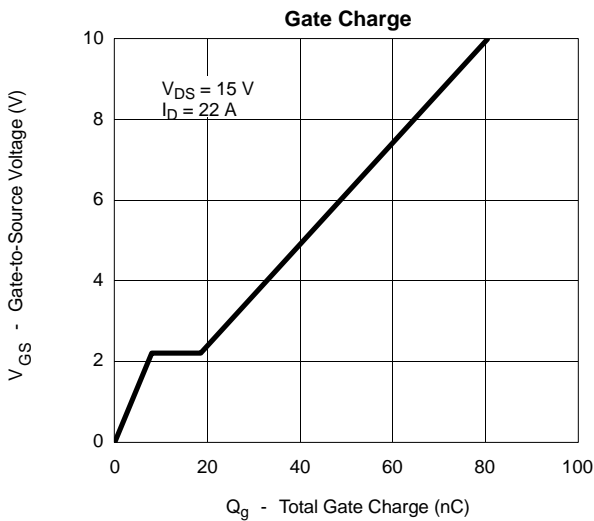
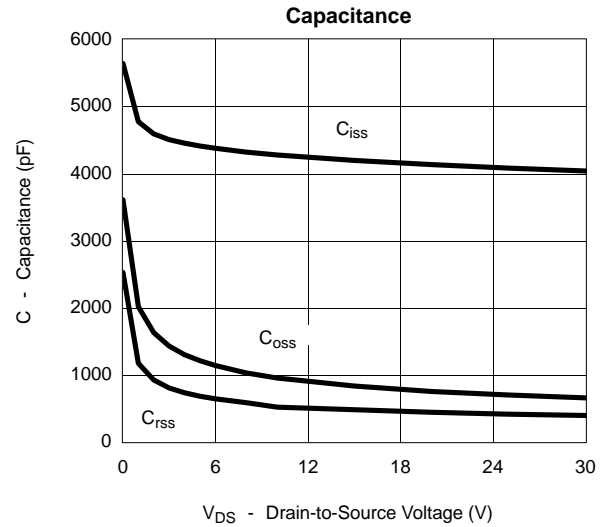
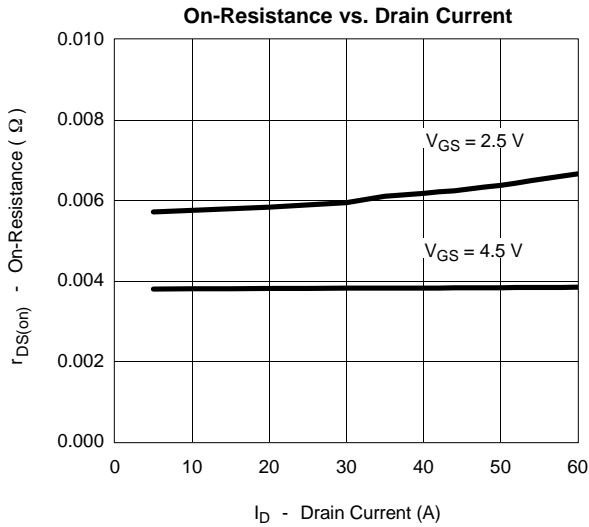
- a. Pulse test; pulse width ≤ 300 μs, duty cycle ≤ 2%.
- b. Guaranteed by design, not subject to production testing.

**TYPICAL CHARACTERISTICS (25 °C UNLESS NOTED)**





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